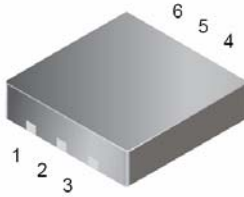


## MLP/DFN -6 Package:



Preliminary dimensions, for reference only  
(JEDEC ultra-thin MQ-229UCDD, except contact layout)  
Dimensions in millimeters  
U.S. Customary dimensions (in.) in brackets, for reference only  
Dimensions exclusive of mold flash, gate burrs, and dambar protrusions  
Exact case and lead configuration at supplier discretion within limits shown

Terminal #1 mark area

Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion)

Reference land pattern layout; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

Hall element (not to scale)

Active area depth 0.233 [0.0092] U.S. Customary dimensions controlling

